



**MAX
245°C**

**MSL
1**

PRODUCT FAMILY	Material	CAS Number	% Normalize for BOM	Wt. Of BOM Item (g)	% by Wt (Comp. Item)	mg/unit	% by Wt Of Unit	ppm
767 14								
Alumina Ceramic	Al2O3	1344-28-1	0.8800	0.2060	87.50%	180.2570	77.00%	770000
	SiO2 (silicon dioxide)	14808-60-7			12.50%	25.7510	11.00%	110000
					100.00%	206.0080		
Conductor Thick Film	Ag	7440-22-4	0.0068	0.0016	99.00%	1.5760	0.67%	6732
	Pd	7440-05-3			1.00%	0.0159	0.01%	68
					100.00%	1.5919		
Resistor Thick Film	RuO2	12036-10-1	0.0079	0.0018	30.00%	0.5548	0.24%	2370
	PbO	1317-36-8			10.00%	0.1849	0.08%	790
	SiO2 (silicon dioxide)	14808-60-7			30.00%	0.5548	0.24%	2370
	B2O3	1303-86-2			30.00%	0.5548	0.24%	2370
					100.00%	1.8494		
Notch Conductor Thick Film	Ag	7440-22-4	0.0113	0.0026	72.02%	1.9052	0.81%	8138
	Pd	7440-05-3			4.20%	0.1111	0.05%	475
	Pt	7440-06-4			23.78%	0.6291	0.27%	2687
					100.00%	2.6453		
Lead Wire	Cu	7440-50-8	0.0376	0.0088	100.00%	8.8022	3.76%	37600
Solder	Pb	7439-92-1	0.0376	0.0088	90.00%	7.9219	3.38%	33840
	Sn	7440-31-5			10.00%	0.8802	0.38%	3760
					100.00%	8.8022		
Covercoat	TiO2	13463-67-7	0.0188	0.0044	50.00%	2.2005	0.94%	9400
	Phenolic Resin	55185-45-0			25.00%	1.1003	0.47%	4700
	Epoxy Resin	25068-38-6			25.00%	1.1003	0.47%	4700
	Sum		1.0000 part weight	0.2341	100.00%	4.4011		
				0.2341				
		Totals:		0.2341		234.10	100.00%	1000000